TOSHIBA Field-Effect Transistor Silicon N-Channel MOS MOS

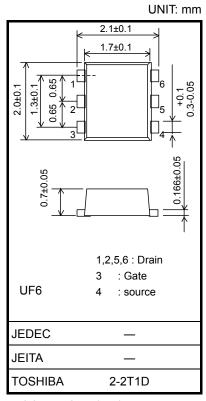
# SSM6K403TU

○ Power Management Switch Applications

- High-Speed Switching Applications
- 1.5V drive
- Low ON-resistance  $R_{on} = 66m\Omega$  (max) (@V<sub>GS</sub> = 1.5V)
  - $R_{on} = 43m\Omega (max) (@V_{GS} = 1.8V)$ 
    - $R_{on} = 32m\Omega (max) (@V_{GS} = 2.5V)$
    - $R_{on} = 28m\Omega \text{ (max)} (@V_{GS} = 4.0V)$

#### Absolute Maximum Ratings (Ta = 25°C) (Note)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	20	V	
Gate-source voltage		V <sub>GSS</sub>	±10	V	
Drain current	DC	I <sub>D</sub>	4.2	А	
	Pulse	I <sub>DP</sub>	8.4	A	
Drain power dissipation		P <sub>D</sub> (Note1)	500	mW	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature		T <sub>stg</sub>	-55~150	°C	



weight: 7.0mg (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on an FR4 board (25.4 mm  $\times$  25.4 mm  $\times$  1.6 t, Cu Pad: 645 mm²)

Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Тур.	Мах	Unit
Drain-source breakdown voltage	V (BR) DSS	$I_D = 1 \text{ mA},  V_{GS} = 0  V$	20	_	_	- V	
Drain-source breakdown vollage		V (BR) DSX	$I_D = 1 \text{ mA}, V_{GS} = -10 \text{V}$	12	_		_
Drain cutoff currer	nt	IDSS	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_	_	1	μA
Gate leakage curre	ent	I <sub>GSS</sub>	$V_{GS} = \pm 10$ V, $V_{DS} = 0$ V	_		±1	μA
Gate threshold vol	tage	V <sub>th</sub>	$V_{DS} = 3 V, I_D = 1 mA$	0.35		1.0	V
Forward transfer a	idmittance	Y <sub>fs</sub>	$V_{DS} = 3 V, I_D = 3.0 A$ (Note2)	10	20	_	S
Drain-source ON-resistance	R <sub>DS</sub> (ON)	$I_D = 3.0 \text{ A}, V_{GS} = 4.0 \text{ V}$ (Note2)	_	19	28	- mΩ	
		$I_D = 3.0 \text{ A}, V_{GS} = 2.5 \text{ V}$ (Note2)		23	32		
		$I_D = 1.0 \text{ A}, V_{GS} = 1.8 \text{ V}$ (Note2)	_	28	43		
		$I_D = 0.5 \text{ A}, V_{GS} = 1.5 \text{ V}$ (Note2)	_	35	66		
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	1050		pF
Output capacitance		C <sub>oss</sub>		_	175		
Reverse transfer capacitance		C <sub>rss</sub>			160		
Total Gate Charge		Qg	$V_{DD} = 10 \text{ V}, \text{ I}_{D} = 4.2 \text{ A}$	_	16.8	_	nC
Gate-Source Charge		Q <sub>gs</sub>		—	12.1		
Gate-Drain Charge		Q <sub>gd</sub>	V <sub>GS</sub> = 4 V	_	4.7		
Switching time	Turn-on time	t <sub>on</sub>	V <sub>DD</sub> = 10 V, I <sub>D</sub> = 1 A	_	18	_	ns
	Turn-off time	t <sub>off</sub>	V <sub>GS</sub> = 0~2.5 V, R <sub>G</sub> = 4.7 Ω	_	32	_	
Drain-source forwa	ard voltage	V <sub>DSF</sub>	$I_D = -4.2 \text{ A}, V_{GS} = 0 \text{ V}$ (Note2)	_	-0.8	-1.2	V

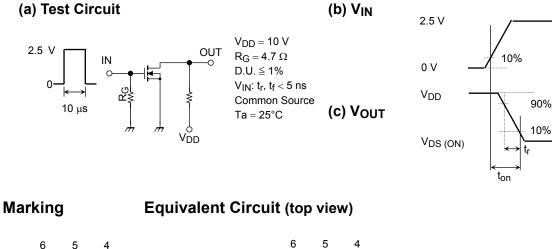
Note 2: Pulse test

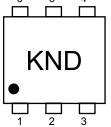
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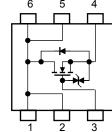
90%

t∩ff

#### Switching Time Test Circuit







#### Notice on Usage

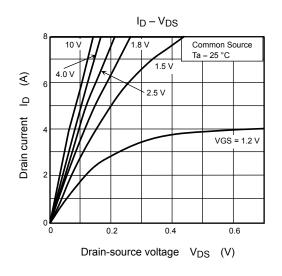
 $V_{th}$  can be expressed as the voltage between gate and source when the low operating current value is  $I_D$  = 1 mA for this product. For normal switching operation,  $V_{GS}$  (on) requires a higher voltage than  $V_{th}$  and  $V_{GS}$  (off) requires a lower voltage than  $V_{th}$ . (The relationship can be established as follows:  $V_{GS}$  (off) <  $V_{th}$  <  $V_{GS}$  (on).)

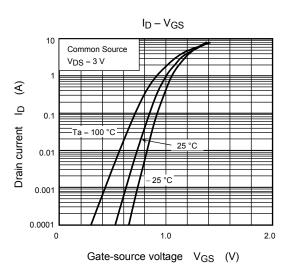
Take this into consideration when using the device.

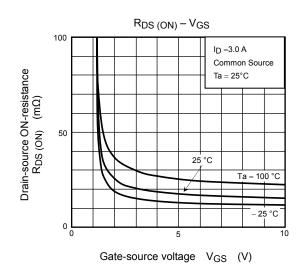
#### **Handling Precaution**

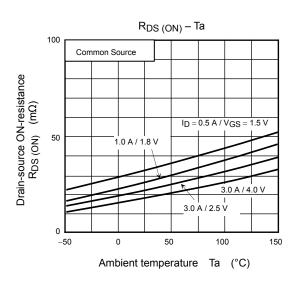
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

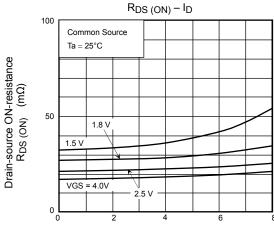
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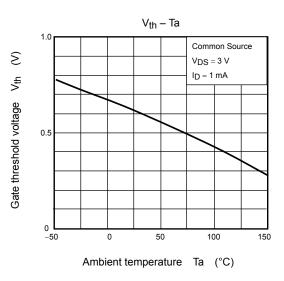




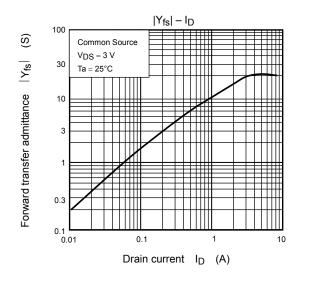


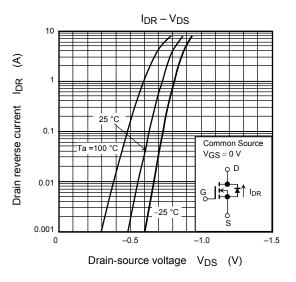


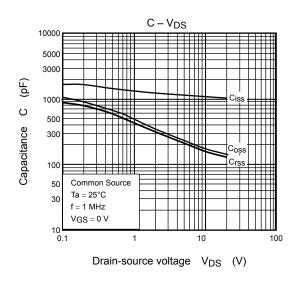
Drain current I<sub>D</sub> (A)

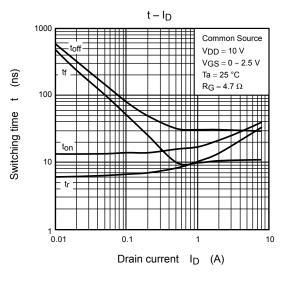


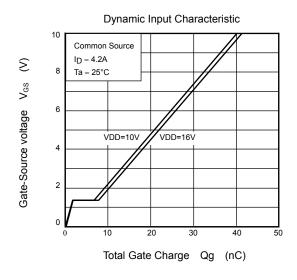
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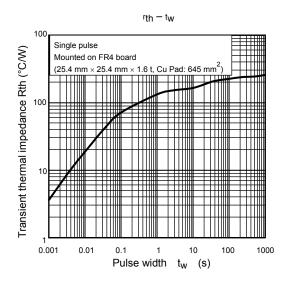


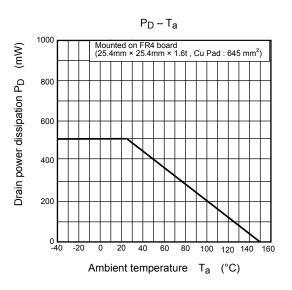






## **TOSHIBA**





#### **RESTRICTIONS ON PRODUCT USE**

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